



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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• 1N6639US THRU 1N6641US AVAILABLE IN JAN, JANTX, JANTXV AND JANS
PER MIL-PRF-19500/609

- SWITCHING DIODES
- NON-CAVITY GLASS PACKAGE
- METALLURGICALLY BONDED

1N6639US
1N6640US
1N6641US

MAXIMUM RATINGS

Operating Temperature: -65°C to +175°C
Storage Temperature: -65°C to +175°C
Operating Current: 300 mA
Derating: 4.6 mA/°C Above $T_{EC} = +110^{\circ}\text{C}$
Surge Current: $I_{FSM} = 2.5\text{A}$, $P_W = 8.3\text{ms}$

ELECTRICAL CHARACTERISTICS @ 25°C, unless otherwise specified.

TYPES	V_{BRR} @ 10 μA	V_{RWM}	I_{R1} @ $T_A = +25^{\circ}\text{C}$ $V_R =$ V_{RWM}	I_{R2} @ $T_A = +150^{\circ}\text{C}$ $V_R =$ V_{RWM}	T_{FR} $I_F =$ $= 200\text{ mA}$	T_{RR} $I_R = 10\text{ mA}$ $I_F = 10\text{ mA}$ $R_L = 100$	C_T $V_R = 0$
	$V_{(pk)}$	$V_{(pk)}$	nA dc	μA dc	ns	ns	pF
1N6639US	100	75	100	100	10	4.0	2.5
1N6640US	75	50	100	100	10	4.0	2.5
1N6641US	75	50	100	100	10	5.0	3.0

FORWARD VOLTAGE:

TYPES	V_F @ I_F		mA (PULSED)
	VdC		
	MIN	MAX	
1N6639US	-	1.20	500
1N6640US	0.54	0.62	1
	0.76	0.86	50
	0.82	0.92	100
	0.87	1.00	200
1N6641US	-	1.10	200

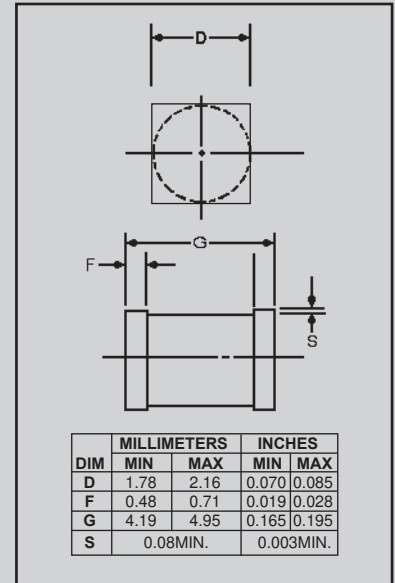


FIGURE 1

DESIGN DATA

CASE: D-5D, Hermetically sealed glass case, per MIL-PRF- 19500/609

LEAD FINISH: Tin / Lead

THERMAL RESISTANCE: ($R_{\theta JEC}$):
50 °C/W maximum at $L = 0$

THERMAL IMPEDANCE: ($Z_{\theta JX}$): 25
°C/W maximum

POLARITY: Cathode end is banded

MOUNTING SURFACE SELECTION:
The Axial Coefficient of Expansion (COE) of this device is approximately + 4PPM / °C. The COE of the Mounting Surface System should be selected to provide a suitable match with this device.



IN6639US thru IN6641US

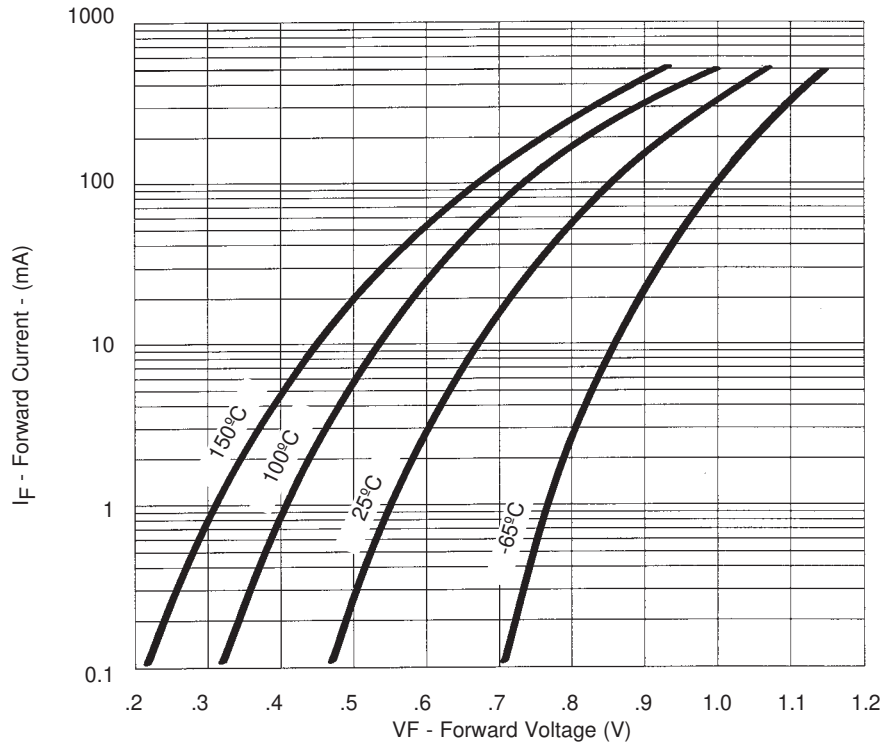


FIGURE 2
Typical Forward Current
vs Forward Voltage

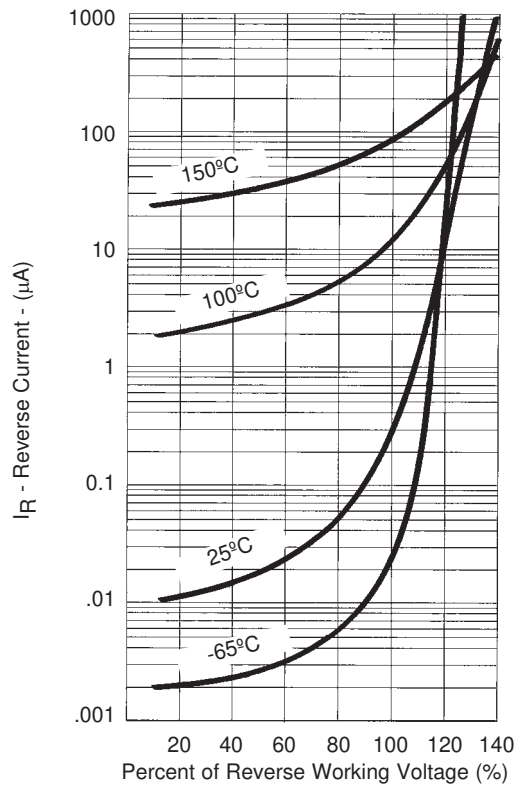


FIGURE 3
Typical Reverse Current
vs Reverse Voltage

NOTE : All temperatures shown on graphs are junction temperatures